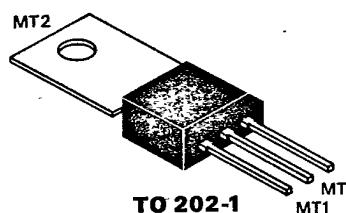


8834750 TAG SEMICONDUCTORS LTD

63C 00791 DT-25-13

TAG SEMICONDUCTORS LTD


**Z0410BE –  
Z0410NE TRIACS**
**4.0 A 200–800 V  
25/25/25 mA**

The Z0410 series of TRIAC's are high performance PNPN devices diffused with TAG's proprietary Top Glass™ Process. These parts are intended for general purpose applications where moderate gate sensitivity is required.

**Absolute Maximum Ratings** TA = 25 °C unless otherwise noted

Parameter	Part Nr.	Symbol	Min.	Max.	Unit	Test Conditions
Repetitive Peak Off State Voltage	<b>Z0410BE</b>	V <sub>DRM</sub>	200		V	
	<b>Z0410DE</b>		400		V	[T <sub>j</sub> =-40 °C to 125 °C]
	<b>Z0410ME</b>		600		V	[R <sub>GK</sub> =1 KΩ]
	<b>Z0410NE</b>		800		V	
On-State Current		I <sub>T(RMS)</sub>	4.0		A	All Conduction Angles T <sub>C</sub> =75 °C
Nonrept. On-State Current		I <sub>TSM</sub>	25		A	Half Cycle, 60 Hz
Nonrept. On-State Current		I <sub>TSM</sub>	22		A	Half Cycle, 50 Hz
Fusing Current		I <sup>2</sup> t	2.4		A <sup>2</sup> s	t=10 ms
Peak Gate Current		I <sub>GM</sub>	1.2		A	10 µs max.
Peak Gate Dissipation		P <sub>GM</sub>	3		W	10 µs max.
Gate Dissipation		P <sub>G(AV)</sub>	0.2		W	20 ms max.
Operating Temperature		T <sub>j</sub>	-40	125	°C	
Storage Temperature		T <sub>stg</sub>	-40	150	°C	
Soldering Temperature		T <sub>sld</sub>		250	°C	1.6 mm from case, 10 s max.

**Electrical Characteristics** TA = 25 °C unless otherwise noted

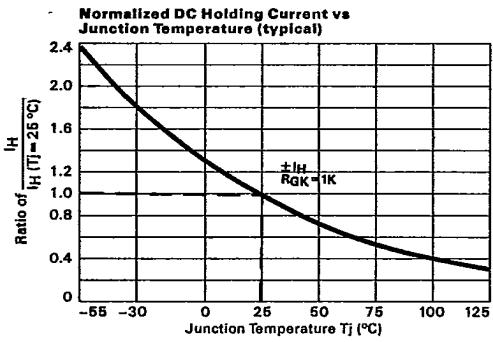
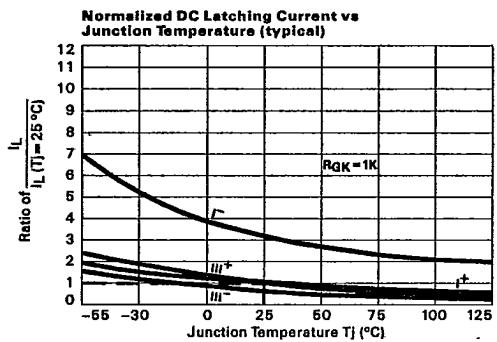
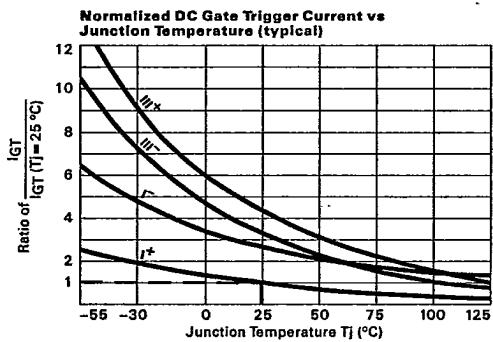
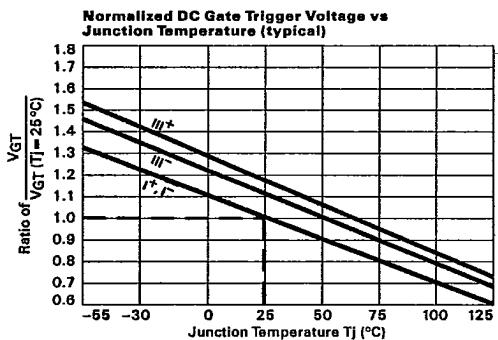
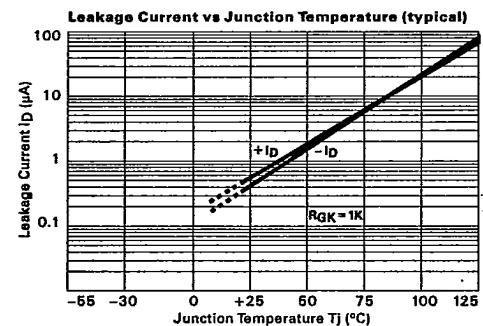
Parameter	Symbol	Min.	Max.	Unit	Test Conditions
Off-State Leakage Current	I <sub>DRM</sub>	200	µA	V <sub>D</sub> =V <sub>DRM</sub> R <sub>GK</sub> =1 KΩ T <sub>j</sub> =125 °C	
Off-State Leakage Current	I <sub>DRM</sub>	5	µA	V <sub>D</sub> =V <sub>DRM</sub> R <sub>GK</sub> =1 KΩ T <sub>j</sub> =25 °C	
On-State Voltage	V <sub>T</sub>	2.10	V	at I <sub>T</sub> =6.0 A, T <sub>j</sub> =25 °C	
On-State Threshold Voltage	V <sub>T(TO)</sub>	0.95	V	T <sub>j</sub> =125 °C	
On-State Slope Resistance	R <sub>T</sub>	180	mΩ	T <sub>j</sub> =125 °C	
Gate Trigger Current	I <sub>GT</sub>  + (1)	25	mA	V <sub>D</sub> =12 V	
	I <sub>GT</sub>  − (2)	25	mA	V <sub>D</sub> =12 V	
	I <sub>GT</sub>  III− (3)	25	mA	V <sub>D</sub> =12 V	
	I <sub>GT</sub>  III+ (4)	25	mA	V <sub>D</sub> =12 V	
Gate Trigger Voltage	V <sub>GT</sub>	2	V	V <sub>D</sub> =12 V	All Quadrants
Holding Current	I <sub>H</sub>	25	mA	R <sub>GK</sub> =1 KΩ	
Critical Rate of Voltage Rise	dv/dt	100		V/µs	V <sub>D</sub> =.67xV <sub>DRM</sub> R <sub>GK</sub> =1 KΩ T <sub>j</sub> =125 °C
Critical Rate of Rise, Off-State	dv/dt <sub>c</sub>	4		V/µs	I <sub>T</sub> =4 A di/dt=1.78 A/ms T <sub>C</sub> =75 °C
Thermal Resistance junc. to case	R <sub>θjc</sub>	7.5	K/W		
Thermal Resistance junc. to amb.	R <sub>θja</sub>	60	K/W		

**Z04**

8834750 TAG SEMICONDUCTORS LTD

63C 00792 DT-25-13

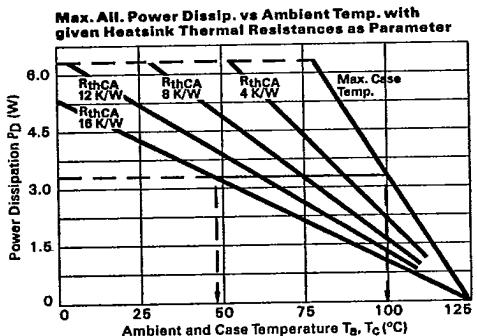
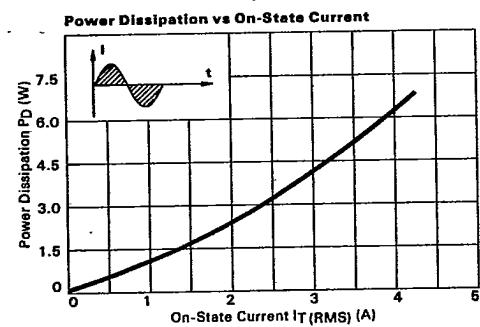
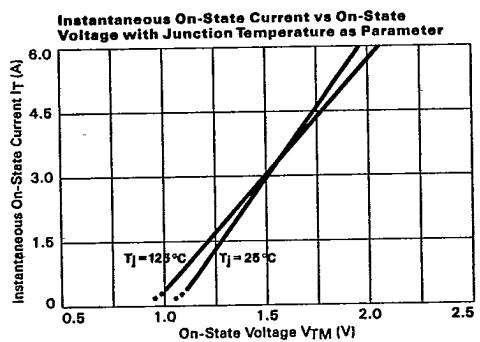
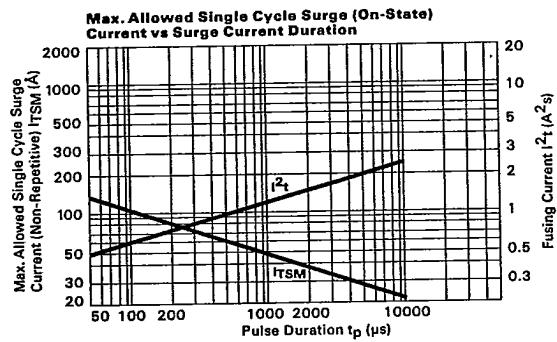
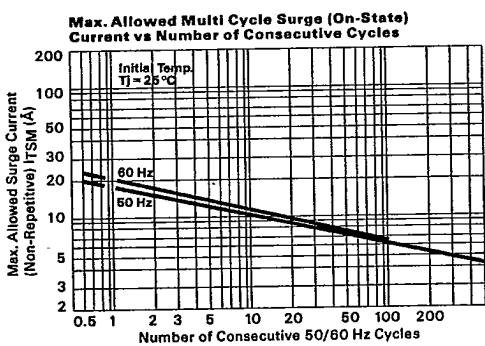
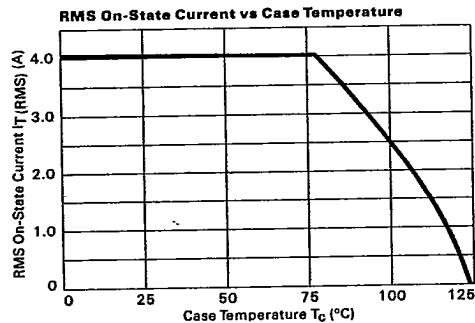
TAG SEMICONDUCTORS LTD

**Typical Characteristics**  
**Z04 - Chips**


8834750 TAG SEMICONDUCTORS LTD

63C 00793 DT-25-13

TAG SEMICONDUCTORS LTD

**Typical Characteristics  
Z04 – Packaged Parts**

  
**Z04**